

# Product data sheet

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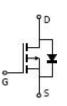


#### APPLICATION

- # Load Switch for Portable Devices
- # DC/DC Converter

#### FEATURE

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	Ι <sub>D</sub>
20.1/	90 mΩ@-4.5V	
-20 V	110 mΩ@-2.5V	-3 A





SOT-23-3L

#### Maximum ratings (T₂=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±8	v
Continuous Drain Current	ID	-3	
Pulsed Drain Current	I <sub>DM</sub>	-10	А
Continuous Source-Drain Diode Current	ls	-0.72	
Maximum Power Dissipation	PD	0.4	W
Thermal Resistance from Junction to Ambient(t ≤5s)	Reja	312.5	°C/W
Junction Temperature	TJ	150	
Storage Temperature	T <sub>stg</sub>	-55 ~+150	Ĉ



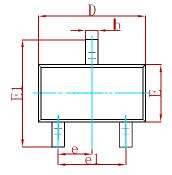
#### T<sub>a</sub>=25 $^{\circ}$ C unless otherwise specified

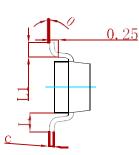
Parameter	Symbol	Test Condition	Min	Тур	Мах	Units	
Static							
Drain-source breakdown voltage	V <sub>(BR)DSS</sub> V <sub>GS</sub> = 0V, I <sub>D</sub> =-250µA		-20				
Gate-source threshold voltage	VGS(th)	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250µA	-0.4		-1	V	
Gate-source leakage	I <sub>GSS</sub>	VDS =0V, VGS =±8V			±100	nA	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V			-1	μA	
	RDS(on)	Vgs =-4.5V, Id =-2.8A		0.080	0.90	Ω	
Drain-source on-state resistance <sup>a</sup>		Vgs =-2.5V, ID =-2.0A		0.90	0.110		
Forward transconductance <sup>a</sup>	<b>g</b> <sub>fs</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2.8A		6.5		S	
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>			405		pF	
Output capacitance	Coss	VDS =-10V,VGS =0V,f =1MHz		75			
Reverse transfer capacitance	Crss			55			
Tatal acts charge	Qg VDS =-10V, VGS =-4	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A		5.5	10		
Total gate charge			3.3	3.3	6	nC	
Gate-source charge	Q <sub>gs</sub>	VDS =-10V, VGS =-2.5V, ID =-3A		0.7			
Gate-drain charge	$Q_{gd}$			1.3			
Gate resistance	Rg	f =1MHz		6.0		Ω	
Turn-on delay time	<b>t</b> d(on)			11	20		
Rise time	tr	V <sub>DD</sub> =-10V, - R <sub>L</sub> =10Ω, I <sub>D</sub> =-1A,		35	60	- ns	
Turn-off delay time	td(off)			30	50		
Fall time	tr	- V <sub>GEN</sub> =-4.5V,Rg=1Ω		10	20		
Drain-source body diode characterist	ics			1			
Continuous source-drain diode current	ls	Tc <b>=25℃</b>			-1.3	A	
Pulse diode forward current <sup>a</sup>	I <sub>SM</sub>				-10		
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> =-0.7A		-0.8	-1.2	V	

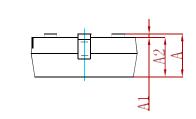




#### PACKAGE MECHANICAL DATA

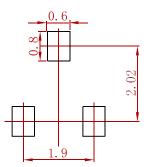






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

#### Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
WPM2341-MS	SOT-23-3	3000



## WPM2341-MS

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